

# Paul Conway

## List of Publications by Year in descending order

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224  
papers

2,661  
citations

257101

24  
h-index

288905

40  
g-index

228  
all docs

228  
docs citations

228  
times ranked

2276  
citing authors

#	ARTICLE	IF	CITATIONS
1	Corrosion characterization of tin-lead and lead free solders in 3.5wt.% NaCl solution. Corrosion Science, 2008, 50, 995-1004.	3.0	195
2	Thermal Interface Materials - A Review of the State of the Art. , 2006, , .		156
3	The effect of pore size and porosity on mechanical properties and biological response of porous titanium scaffolds. Materials Science and Engineering C, 2017, 77, 219-228.	3.8	132
4	Evolution of CuSn intermetallics between molten SnAgCu solder and Cu substrate. Acta Materialia, 2008, 56, 4291-4297.	3.8	111
5	Characteristics of intermetallics and micromechanical properties during thermal ageing of Sn-Ag-Cu flip-chip solder interconnects. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2005, 391, 95-103.	2.6	94
6	Preservation in the Age of Google: Digitization, Digital Preservation, and Dilemmas. Library Quarterly, 2010, 80, 61-79.	0.4	79
7	An industrial evaluation of an Industry 4.0 reference architecture demonstrating the need for the inclusion of security and human components. Computers in Industry, 2019, 108, 37-44.	5.7	57
8	Manufacture of a human mesenchymal stem cell population using an automated cell culture platform. Cytotechnology, 2007, 55, 31-39.	0.7	55
9	Embedded programming and real-time signal processing of swimming strokes. Sports Engineering, 2011, 14, 1-14.	0.5	54
10	Initial formation of CuSn intermetallic compounds between molten SnAgCu solder and Cu substrate. Scripta Materialia, 2009, 60, 333-335.	2.6	53
11	Electroless nickel bumping of aluminum bondpads. I. Surface pretreatment and activation. IEEE Transactions on Components and Packaging Technologies, 2002, 25, 87-97.	1.4	50
12	Evolution of microstructure and electrical conductivity of electroless copper deposits on a glass substrate. Thin Solid Films, 2012, 520, 6095-6099.	0.8	49
13	Modelling of Ag <sub>3</sub> Sn coarsening and its effect on creep of Sn-Ag eutectics. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2006, 427, 60-68.	2.6	48
14	Integrated optical and electronic interconnect PCB manufacturing research. Circuit World, 2010, 36, 5-19.	0.7	40
15	Micromechanical modelling of SnAgCu solder joint under cyclic loading: Effect of grain orientation. Computational Materials Science, 2007, 39, 187-197.	1.4	39
16	Reliability issues in Pb-free solder joint miniaturization. Journal of Electronic Materials, 2006, 35, 1761-1772.	1.0	38
17	The Evolution of Pd-Sn Catalytic Surfaces in Electroless Copper Deposition. Journal of the Electrochemical Society, 2011, 158, D172.	1.3	38
18	Design and Implementation of an Integrated Performance Monitoring Tool for Swimming to Extract Stroke Information at Real Time. IEEE Transactions on Human-Machine Systems, 2013, 43, 199-213.	2.5	35

#	ARTICLE	IF	CITATIONS
19	The categorisation of swimming start performance with reference to force generation on the main block and footrest components of the Omega OSB11 start blocks. <i>Journal of Sports Sciences</i> , 2013, 31, 468-478.	1.0	35
20	Effective modeling of the reflow soldering process: basis, construction, and operation of a process model. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology Part C Manufacturing</i> , 1998, 21, 126-133.	0.4	34
21	Digital transformations and the archival nature of surrogates. <i>Archival Science</i> , 2015, 15, 51-69.	0.6	34
22	Formation of Ag <sub>3</sub> Sn plates in SnAgCu solder bumps. <i>Materials Science &amp; Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2010, 527, 2588-2591.	2.6	31
23	Performance measurement and KPIs for remanufacturing. <i>Journal of Remanufacturing</i> , 2015, 5, 1.	1.6	28
24	Cyber-Physical Systems in the re-use, refurbishment and recycling of Used Electrical and Electronic Equipment. <i>Journal of Cleaner Production</i> , 2018, 170, 351-361.	4.6	28
25	Microstructure and shear strength evolution of Sn-Ag-Cu solder bumps during aging at different temperatures. <i>Journal of Electronic Materials</i> , 2006, 35, 388-398.	1.0	26
26	Microstructural considerations for ultrafine lead free solder joints. <i>Microelectronics Reliability</i> , 2007, 47, 1997-2006.	0.9	23
27	Development of a real time system for monitoring of swimming performance. <i>Procedia Engineering</i> , 2010, 2, 2707-2712.	1.2	23
28	Formation of Sn dendrites and SnAg eutectics in a SnAgCu solder. <i>Scripta Materialia</i> , 2009, 61, 682-685.	2.6	21
29	Fabrication of Polymer Waveguides by Laser Ablation Using a 355 nm Wavelength Nd:YAG Laser. <i>Journal of Lightwave Technology</i> , 2011, 29, 3566-3576.	2.7	21
30	Electroless nickel bumping of aluminum bondpads. II. Electroless nickel plating. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2002, 25, 98-105.	1.4	20
31	Modeling the digital content landscape in universities. <i>Library Hi Tech</i> , 2008, 26, 342-354.	3.7	20
32	Low frequency induction heating for the sealing of plastic microfluidic systems. <i>Microfluidics and Nanofluidics</i> , 2010, 9, 243-252.	1.0	20
33	Accelerometer Profile Recognition of Swimming Strokes (P17). , 0, , 81-87.		19
34	Mesomechanical modelling of SnAgCu solder joints in flip chip. <i>Computational Materials Science</i> , 2008, 43, 199-211.	1.4	18
35	Modes of Seeing: Digitized Photographic Archives and the Experienced User. <i>American Archivist</i> , 2010, 73, 425-462.	0.1	18
36	A modelling tool for the thermal optimisation of the reflow soldering of printed circuit assemblies. <i>Finite Elements in Analysis and Design</i> , 1998, 30, 47-63.	1.7	16

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37	Precision high temperature lead-free solder interconnections by means of high-energy droplet deposition techniques. CIRP Annals - Manufacturing Technology, 2002, 51, 177-180.	1.7	16
38	The effect of microstructural and geometrical features on the reliability of ultrafine flip chip microsolder joints. Journal of Electronic Materials, 2004, 33, 1227-1235.	1.0	16
39	Dynamic signature for tumble turn performance in swimming. Procedia Engineering, 2010, 2, 3391-3396.	1.2	15
40	Product life cycle information management in the electronics supply chain. Proceedings of the Institution of Mechanical Engineers, Part B: Journal of Engineering Manufacture, 2012, 226, 1388-1400.	1.5	15
41	Kinetic Monte Carlo simulation of the electrodeposition of polycrystalline copper: Effects of substrates and deposition parameters on the microstructure of deposits. Electrochimica Acta, 2013, 97, 132-142.	2.6	15
42	Effects of the microstructure of copper through-silicon vias on their thermally induced linear elastic mechanical behavior. Electronic Materials Letters, 2014, 10, 281-292.	1.0	15
43	Comparison of in-sight and handheld navigation devices toward supporting industry 4.0 supply chains: First and last mile deliveries at the human level. Applied Ergonomics, 2020, 82, 102928.	1.7	15
44	The impact of multimodal pore size considered independently from porosity on mechanical performance and osteogenic behaviour of titanium scaffolds. Materials Science and Engineering C, 2021, 124, 112026.	3.8	15
45	The process modelling of the infra-red reflow soldering of printed circuit board assemblies. Journal of Electronics Manufacturing, 1992, 02, 23-29.	0.4	14
46	Effective modeling of the reflow soldering process: use of a modeling tool for product and process design. IEEE Transactions on Components, Packaging and Manufacturing Technology Part C Manufacturing, 1998, 21, 165-171.	0.4	14
47	Variation in the line stability of an inkjet printed optical waveguide-applicable material. , 2008, , .		14
48	Characterizing the swimming tumble turn using acceleration data. Proceedings of the Institution of Mechanical Engineers, Part P: Journal of Sports Engineering and Technology, 2012, 226, 3-15.	0.4	14
49	Archival quality and long-term preservation: a research framework for validating the usefulness of digital surrogates. Archival Science, 2011, 11, 293-309.	0.6	13
50	CO2 laser micromachining of optical waveguides for interconnection on circuit boards. Optics and Lasers in Engineering, 2012, 50, 1752-1756.	2.0	13
51	Preserving Imperfection: Assessing the Incidence of Digital Imaging Error in HathiTrust. Preservation, Digital Technology and Culture, 2013, 42, 17-30.	0.2	13
52	Glass as a Substrate for High Density Electrical Interconnect. , 2008, , .		12
53	Kinetic Monte Carlo simulation of kinetically limited copper electrocrystallization on an atomically even surface. Electrochimica Acta, 2009, 54, 6941-6948.	2.6	12
54	Polymer optical waveguide fabrication using laser ablation. , 2009, , .		12

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55	New lifecycle monitoring system for electronic manufacturing with embedded wireless components. Circuit World, 2010, 36, 33-39.	0.7	12
56	Process variables in the reflow soldering of surface mount. , 0, , .		11
57	Simulation and Interpretation of Wetting Balance Tests Using the Surface Evolver. Journal of Electronic Packaging, Transactions of the ASME, 1996, 118, 134-141.	1.2	11
58	Thermo-mechanical properties and regression models of alloys: AISI 305, CK 60, CuBe2 and Laiton MS 63. Journal of Materials Processing Technology, 2005, 168, 152-163.	3.1	11
59	Effect of solder bump geometry on the microstructure of Sn <sup>3.5</sup> wt% Ag on electroless nickel immersion gold during solder dipping. Journal of Materials Research, 2005, 20, 649-658.	1.2	11
60	Process Optimisation and Characterization of Excimer Laser Drilling of Microvias in Glass. , 2007, , .		11
61	A computational interface for thermodynamic calculations software MTDATA. Calphad: Computer Coupling of Phase Diagrams and Thermochemistry, 2008, 32, 129-134.	0.7	11
62	Modeling of interfacial intermetallic compounds in the application of very fine lead-free solder interconnections. Microsystem Technologies, 2009, 15, 101-107.	1.2	11
63	The development of an inexpensive passive marker system for the analysis of starts and turns in swimming. Procedia Engineering, 2010, 2, 2727-2733.	1.2	11
64	The Effect of Knee Angle on Force Production, in Swimming Starts, using the OSB11 Block. Procedia Engineering, 2012, 34, 801-806.	1.2	11
65	Archival Preservation: Definitions for Improving Education and Training. Restaurator, 1989, 10, .	0.2	10
66	Effects of plies assembling on textile composite cellular structures. Materials & Design, 2007, 28, 857-870.	5.1	10
67	Integrated optical and electronic interconnect printed circuit board manufacturing. Circuit World, 2008, 34, 21-26.	0.7	10
68	Cost estimation for remanufacture with limited and uncertain information using case based reasoning. Journal of Remanufacturing, 2015, 5, 1.	1.6	10
69	Effective transient process modelling of the reflow soldering of printed circuit assemblies. , 0, , .		9
70	UNDER BUMP METALLISATION OF FINE PITCH FLIP-CHIP USING ELECTROLESS NICKEL DEPOSITION. Journal of Electronics Manufacturing, 2000, 10, 161-170.	0.4	9
71	Kinetic Monte Carlo simulation of electrodeposition of polycrystalline Cu. Electrochemistry Communications, 2009, 11, 2207-2211.	2.3	9
72	Integrated simulation tool for quality support in the low-volume high-complexity electronics manufacturing domain. International Journal of Production Research, 2010, 48, 45-68.	4.9	9

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73	The effect of start block configuration and swimmer kinematics on starting performance in elite swimmers using the Omega OSB11 block. <i>Procedia Engineering</i> , 2011, 13, 141-147.	1.2	9
74	Swimming Turn Technique Optimisation by Real-Time Measurement of Foot Pressure and Position. <i>Procedia Engineering</i> , 2012, 34, 586-591.	1.2	9
75	The Effect of Energy Density and Nb Content on the Microstructure and Mechanical Properties of Selective Laser Melted Ti-(10-30 wt.%) Nb. <i>Journal of Materials Engineering and Performance</i> , 2021, 30, 8771-8783.	1.2	9
76	STATISTICAL OPTIMISATION OF THERMOPLASTIC INJECTION MOULDING PROCESS FOR THE ENCAPSULATION OF ELECTRONIC SUBASSEMBLY. <i>Journal of Electronics Manufacturing</i> , 2000, 10, 171-179.	0.4	8
77	Embedding of electronics within thermoplastic polymers using injection moulding technique. , 0, , .		8
78	Challenges in the manufacture of glass substrates for electrical and optical interconnect. <i>Circuit World</i> , 2007, 33, 22-30.	0.7	8
79	Fabrication of a Polymeric Optical Waveguide-On-Flex Using Electrostatic-Induced Lithography. <i>IEEE Photonics Technology Letters</i> , 2010, 22, 957-959.	1.3	8
80	Development of a pressure sensor for swimming turns. <i>Procedia Engineering</i> , 2011, 13, 126-132.	1.2	8
81	A generalized computational interface for combined thermodynamic and kinetic modeling. <i>Calphad: Computer Coupling of Phase Diagrams and Thermochemistry</i> , 2011, 35, 391-395.	0.7	8
82	Sustainable production in the UK: a tool to support printed circuit assembly (PCA) manufacturing. <i>International Journal of Computer Integrated Manufacturing</i> , 2013, 26, 346-364.	2.9	8
83	Aerosol-assisted fabrication of tin-doped indium oxide ceramic thin films from nanoparticle suspensions. <i>Journal of Materials Chemistry C</i> , 2016, 4, 5739-5746.	2.7	8
84	Addition of Sn to TiNb alloys to improve mechanical performance and surface properties conducive to enhanced cell activity. <i>Materials Science and Engineering C</i> , 2020, 115, 110839.	3.8	8
85	Countermovement jump performance in elite male and female sprinters and high jumpers. <i>Proceedings of the Institution of Mechanical Engineers, Part P: Journal of Sports Engineering and Technology</i> , 2021, 235, 131-138.	0.4	8
86	Automated adaptive control of the reflow soldering of electronic assemblies. , 0, , .		7
87	Copper Deposition and Patterning for Glass Substrate Manufacture. , 2007, , .		7
88	Materials behaviour and intermetallics characteristics in the reaction between SnAgCu and Snâ€Pb solder alloys. <i>Journal of Materials Science</i> , 2007, 42, 4076-4086.	1.7	7
89	Root cause analysis support for quality improvement in electronics manufacturing. <i>Assembly Automation</i> , 2011, 31, 38-46.	1.0	7
90	Design and implementation of a user-centric swimming performance monitoring tool. <i>Proceedings of the Institution of Mechanical Engineers, Part P: Journal of Sports Engineering and Technology</i> , 2011, 225, 213-229.	0.4	7

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91	Effects of Stress and Electromigration on Microstructural Evolution in Microbumps of Three-Dimensional Integrated Circuits. IEEE Transactions on Device and Materials Reliability, 2014, 14, 995-1004.	1.5	7
92	Comparison of Selective Laser Melted Commercially Pure Titanium Sheet-Based Triply Periodic Minimal Surfaces and Trabecular-Like Strut-Based Scaffolds for Tissue Engineering. Advanced Engineering Materials, 2022, 24, 2100527.	1.6	7
93	Grain Features of SnAgCu Solder and their Effect on Mechanical Behavior of Micro-Joints. , 0, , .		6
94	Characterization of printed solder paste excess and bridge related defects. , 2008, , .		6
95	Surface characterisation of plasma treated flexible substrates for waveguide-on-flex application. Surface and Coatings Technology, 2009, 203, 3741-3749.	2.2	6
96	Productionisation issues for commercialisation of microfluidic based devices. Sensor Review, 2009, 29, 349-354.	1.0	6
97	Packaging of Microfluidic Devices for Fluid Interconnection Using Thermoplastics. Journal of Microelectromechanical Systems, 2009, 18, 354-362.	1.7	6
98	Development of a wireless sensor network for embedded monitoring of human motion in a Harsh environment. , 2011, , .		6
99	Information structure required for life-cycle monitoring of electronic products. Proceedings of the Institution of Mechanical Engineers, Part B: Journal of Engineering Manufacture, 2012, 226, 1612-1627.	1.5	6
100	Processing-Structure-Protrusion Relationship of 3-D Cu TSVs: Control at the Atomic Scale. IEEE Journal of the Electron Devices Society, 2019, 7, 1270-1276.	1.2	6
101	A Multi-sensor System for Monitoring the Performance of Elite Swimmers. Communications in Computer and Information Science, 2012, , 350-362.	0.4	6
102	SMD Reflow Soldering: A Thermal Process Model. CIRP Annals - Manufacturing Technology, 1991, 40, 21-24.	1.7	5
103	Observed Phenomenology of the Interaction between Solder Paste and Soldering Processes. Soldering and Surface Mount Technology, 1994, 6, 8-11.	0.9	5
104	Scanning acoustic microscopy investigation of engineered flip-chip delamination. , 0, , .		5
105	Thermal, mechanical and optical modelling of VCSEL packaging. , 0, , .		5
106	Solderability of electroless deposited Ni-P coatings with Sn-3.8Ag-0.7Cu and Sn-3.5Ag lead-free solder alloys. Circuit World, 2005, 31, 32-39.	0.7	5
107	Evaluating a new flexible soldering system for electronics small and medium enterprises. Proceedings of the Institution of Mechanical Engineers, Part B: Journal of Engineering Manufacture, 2008, 222, 273-283.	1.5	5
108	Interfacial Reaction Between Molten Sn-Bi Based Solders and Electroless Ni-P Coatings for Liquid Solder Interconnects. IEEE Transactions on Components and Packaging Technologies, 2008, 31, 574-585.	1.4	5

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109	Innovative Optical and Electronic Interconnect Printed Circuit Board Manufacturing research. , 2008, , ,		5
110	Implementing PREMIS: a case study of the Florida Digital Archive. Library Hi Tech, 2010, 28, 273-289.	3.7	5
111	A database system for decision support in low-volume electronics assembly. Proceedings of the Institution of Mechanical Engineers, Part B: Journal of Engineering Manufacture, 2011, 225, 1411-1430.	1.5	5
112	Development of a Novel System for Monitoring Strength and Conditioning in Elite Athletes. Procedia Engineering, 2012, 34, 496-501.	1.2	5
113	Development of a wireless sensor network for use as an automated system for monitoring swimming starts. Proceedings of the Institution of Mechanical Engineers, Part P: Journal of Sports Engineering and Technology, 2013, 227, 184-195.	0.4	5
114	Microstructural and Reliability Issues of TSV. Springer Series in Advanced Microelectronics, 2017, , 71-99.	0.3	5
115	An interoperable semantic service toolset with domain ontology for automated decision support in the end-of-life domain. Future Generation Computer Systems, 2020, 112, 848-858.	4.9	5
116	Physico-chemical characterisation of Ti-Nb-Sn alloys surfaces and their osteogenic properties. Surface and Coatings Technology, 2020, 403, 126439.	2.2	5
117	Analysis of the Micro-Mechanical Properties in Aged Lead-Free, Fine Pitch Flip Chip Joints. , 2003, , ,		5
118	The value chain in multinational electronics manufacturing enterprises operating in newly industrialized countries. Journal of Electronics Manufacturing, 1992, 02, 161-167.	0.4	4
119	Offshore development of electronic products. Engineering Management Journal, 1994, 4, 185.	0.0	4
120	Design and Manufacture by Foreign Electronics Multi-Nationals in Singapore and Taiwan: Product Responsibilities in a Global Environment. Proceedings of the Institution of Mechanical Engineers, Part B: Journal of Engineering Manufacture, 1996, 210, 221-231.	1.5	4
121	Experimental Investigation of the Formation of Surface Mount Solder Joints. Journal of Electronic Packaging, Transactions of the ASME, 1996, 118, 223-228.	1.2	4
122	Analysis of the Micro-Mechanical Properties in Aged Lead-Free, Fine Pitch Flip Chip Joints. Journal of Electronic Packaging, Transactions of the ASME, 2004, 126, 359-366.	1.2	4
123	A case-based reasoning approach for low volume, high added value electronics. , 2006, , ,		4
124	Analysis of Stress Distribution in SnAgCu Solder Joint. Applied Mechanics and Materials, 2006, 5-6, 359-366.	0.2	4
125	Complex Low Volume Electronics Simulation Tool to Improve Yield and Reliability. Electronics Manufacturing Technology Symposium (IEMT), IEEE/CPMT International, 2007, , ,	0.0	4
126	Integrated modelling for simulation in the electronics manufacturing domain. , 2009, , ,		4

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127	DEVELOPMENT AND R&D CAPABILITY AT MANUFACTURING SITES: ELECTRONICS MULTINATIONALS IN SINGAPORE AND TAIWAN. Production and Operations Management, 1997, 6, 131-149.	2.1	4
128	Design and construction of large-area flexible printed-circuit automotive electrical interconnection harnesses. Proceedings of the Institution of Mechanical Engineers, Part D: Journal of Automobile Engineering, 2010, 224, 785-797.	1.1	4
129	Excimer laser machining of microvias in glass substrates for the manufacture of high density interconnects. Applied Physics B: Lasers and Optics, 2012, 108, 137-147.	1.1	4
130	A wireless sensor system for monitoring the performance of a swimmer's tumble turn. Proceedings of the Institution of Mechanical Engineers, Part P: Journal of Sports Engineering and Technology, 2013, 227, 161-171.	0.4	4
131	Personalised Controller Strategies for Next Generation Intelligent Adaptive Electric Bicycles. IEEE Transactions on Intelligent Transportation Systems, 2021, 22, 7814-7825.	4.7	4
132	Solderability testing of alternate component termination materials with lead free solder alloys. , 0, , .		3
133	The application of IR thermography to process monitoring and control of reflow soldering. Soldering and Surface Mount Technology, 1998, 10, 13-18.	0.9	3
134	Development of a Closed-Loop Controlled Reflow Soldering Process. CIRP Annals - Manufacturing Technology, 1999, 48, 5-8.	1.7	3
135	Inter-dependence of processing and alloy composition on the reliability of Sn-based lead free solders in fine pitch FCOB interconnection. , 0, , .		3
136	A Review on 3D Integrated Approaches in Multimode Optical Polymeric Waveguide Fabrication. , 2007, , .		3
137	Crystallographic Structure and Mechanical Behaviour of SnAgCu Solder Interconnects under a Constant Loading Rate. , 2007, , .		3
138	Plastic Packaging Using Low Frequency Induction Heating (LFIH) For Microsystems. , 2008, , .		3
139	Packaging of polymer based microfluidic systems using low frequency induction heating (LFIH). , 2008, , .		3
140	Design of an end-user centric information interface from data-rich performance analysis tools in elite swimming. Procedia Engineering, 2010, 2, 2713-2719.	1.2	3
141	A Novel Instrumented Cycle Ergometer with Automated In-Situ Capabilities. , 2013, , .		3
142	Assessing wireless inertia measurement units for monitoring athletics sprint performance. , 2014, , .		3
143	A Method for Quantification of the Effects of Size and Geometry on the Microstructure of Miniature Interconnects. Journal of Electronic Materials, 2014, 43, 618-629.	1.0	3
144	In-silico design and experimental validation of TiNbTaZrMoSn to assess accuracy of mechanical and biocompatibility predictive models. Journal of the Mechanical Behavior of Biomedical Materials, 2021, 124, 104858.	1.5	3

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145	Business Process Modelling and its Use Within an Elite Training Environment (P15). , 0, , 73-80.		3
146	Microstructure and Mechanical Reliability Issues of TSV. Springer Series in Advanced Microelectronics, 2021, , 71-105.	0.3	3
147	Comparison of Selective Laser Melted Commercially Pure Titanium Sheetâ€Based Triply Periodic Minimal Surfaces and Trabecularâ€Like Strutâ€Based Scaffolds for Tissue Engineering. Advanced Engineering Materials, 2022, 24, .	1.6	3
148	Under bump metallisation of fine pitch flip-chip using electroless nickel deposition. , 0, , .		2
149	Foresight Vehicle: Physical Media for Automotive Multiplex Networks Implemented on Large Area Flexible Printed Circuit Boards. , 0, , .		2
150	Electromagnetic compatibility performance of large area flexible printed circuit automotive harness. Proceedings of the Institution of Mechanical Engineers, Part D: Journal of Automobile Engineering, 2004, 218, 667-673.	1.1	2
151	Materials and processes issues in fine pitch eutectic solder flip chip interconnection. , 0, , .		2
152	Integration and Packaging of Microsystems by Polymer Overmoulding. , 2006, , .		2
153	Materials and Processes Issues in Fine Pitch Eutectic Solder Flip Chip Interconnection. IEEE Transactions on Components and Packaging Technologies, 2006, 29, 869-876.	1.4	2
154	Modeling the interdependence of processing and alloy composition on the evolution of microstructure in Sn-based lead-free solders in fine pitch flip chip. IEEE Transactions on Components and Packaging Technologies, 2006, 29, 98-104.	1.4	2
155	Challenges in the Manufacture of Glass Substrates for Electrical and Optical Interconnect. , 2006, , .		2
156	Crystallographic Features of Copper Column Growth by Reversible Pulse Current Electrodeposition. , 2007, , .		2
157	An investigation of electroless copper films deposited on glass. , 2008, , .		2
158	Virtual prototyping of flexible soldering cells for electronic manufacture. Proceedings of the Institution of Mechanical Engineers, Part B: Journal of Engineering Manufacture, 2008, 222, 711-722.	1.5	2
159	A simulation module for supporting the manufacture of high value added electronics manufacturing. , 2008, , .		2
160	Reliability of Fine Pitch Snâ€3.8Agâ€0.7Cu Flip Chip Solder Joints With Different Connection Pads on PCB. Journal of Electronic Packaging, Transactions of the ASME, 2008, 130, .	1.2	2
161	Heterogeneous Intragranular Inelastic Behavior of a Sn-Ag-Cu Alloy. Journal of Electronic Materials, 2009, 38, 2429-2435.	1.0	2
162	A systems integration perspective to manufacturing modelling and simulation. , 2010, , .		2

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163	Polymer bonding by induction heating for microfluidic applications. , 2010, , .		2
164	Effect of microstructure on thermal-mechanical stress in 3D copper TSV structures. , 2011, , .		2
165	Linkages Between Microstructure and Mechanical Properties of Ultrafine Interconnects. Journal of Electronic Materials, 2013, 42, 263-271.	1.0	2
166	Microstructure-based multiphysics modeling for semiconductor integration and packaging. Science Bulletin, 2014, 59, 1696-1708.	1.7	2
167	An atomistic study of copper extrusion in through-silicon-via using phase field crystal models. , 2016, , .		2
168	Enhanced interfacial adhesion and mechanical performance of lightweight polyurethane foam reinforced with a low content of aligned magnetised short carbon fibres. Composite Interfaces, 2021, 28, 309-328.	1.3	2
169	Enabling Technologies for Robust Performance Monitoring (P10). , 0, , 45-54.		2
170	Secure Document and Asset Tracking. Journal of Communications Software and Systems, 2017, 9, 24.	0.6	2
171	A process model of the infra-red reflow soldering of printed circuit board assemblies. , 0, , .		1
172	An environmental comparison of solder and conductive adhesives for SMT interconnect. , 0, , .		1
173	Multichip modules (MCMs): a review of the status quo. Journal of Electronics Manufacturing, 1993, 03, 1-11.	0.4	1
174	Investigation of a solder bumping technique for flip-chip interconnection. Soldering and Surface Mount Technology, 2000, 12, 7-14.	0.9	1
175	Foresight Vehicle: Large Area Flexible Circuits for Automotive Applications Manufacturing Technology - A Review of Process Options. , 2002, , .		1
176	Foresight Vehicle: Specification and Acceptability Criteria for Copper-Clad Dielectric Materials Used in Large Automotive Flexible Printed Circuits. , 2002, , .		1
177	Design of a turbulence-enhanced deaggregation system for dry powder formulations. , 0, , .		1
178	Interfacial reactions between Pb-free solders and metallized substrate surfaces. , 0, , .		1
179	Sub-100 micron pitch stencil printing for wafer scale bumping. , 2005, , .		1
180	Polymer Overmoulding for Microfluidic Device Packaging and System Integration. , 0, , .		1

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181	Novel approach to reflow oven design to control and optimise lead free soldering process. , 2006, , .		1
182	Glass Multilayer Lamination for PCB Manufacture using Pressure Assisted Low Temperature Bonding. , 2007, , .		1
183	The effect of surface modification on adhesion of polymer waveguide on flexible substrate. , 2008, , .		1
184	Controlling Interfacial Interpenetration of Polymer Waveguide Deposited on Plasma Treated Flexible Substrate. , 2008, , .		1
185	Excimer laser micromachining of glass substrates. , 2008, , .		1
186	Development of an automated cycle ergometer. Procedia Engineering, 2011, 13, 69-74.	1.2	1
187	Combining business process and failure modelling to increase yield in electronics manufacturing. Proceedings of the Institution of Mechanical Engineers, Part B: Journal of Engineering Manufacture, 2011, 225, 264-281.	1.5	1
188	A multi-electrode array (MEA) biochip with excimer laser-produced micro-well features. Circuit World, 2012, 38, 30-37.	0.7	1
189	Image processing algorithms to extract swimming tumble turn signatures in real-time. , 2012, , .		1
190	Size and geometry effects on microstructural evolution in Sn microbumps during isothermal aging. , 2013, , .		1
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